

Title (en)

PROCESS AND DEVICE FOR MANUFACTURING LACQUED WIRES WITH MOLTED RESINS

Publication

EP 0448999 A3 19920506 (DE)

Application

EP 91103406 A 19910306

Priority

DE 4010306 A 19900330

Abstract (en)

[origin: EP0448999A2] For manufacturing lacquered wires with virtually solvent-free molten resins, as far as the process is concerned, the bare wire is prepared for coating in a way dependent on the material, a supply of resin for the coating is melted and kept by the application of heat at a temperature to obtain suitable viscosity for coating, the molten resin is pumped along under positive pressure against the direction of movement of the wire over a predetermined length of the said wire, over its entire circumference, parts of the resin coating the wire, whereas the excess resin and the resin coating the wire and then calibrated to a predetermined circumferential size is returned to the supply. The resin coating the wire is subsequently cured. As far as the device is concerned, a coating device comprises a wire preparing device, in particular for the wire to be cleaned, heated and the like for its material-dependent preparation, a resin preparation device, a resin application device, the resin preparation device and resin application device being arranged in the form of a closed circuit, as well as a stoving oven. <IMAGE>

IPC 1-7

H01B 13/06

IPC 8 full level

B05C 3/12 (2006.01); **H01B 7/02** (2006.01); **H01B 13/00** (2006.01); **H01B 13/06** (2006.01); **H01B 13/16** (2006.01)

CPC (source: EP US)

H01B 13/065 (2013.01 - EP US)

Citation (search report)

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- [A] US 4258646 A 19810331 - KLOCZEWSKI HAROLD A, et al
- [A] FR 2088681 A5 19720107 - BECK & CO AG
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WO2007121499A1; EP2930723A3; DE19602705C1; EP0767471A1

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